

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-11: (Canceled).

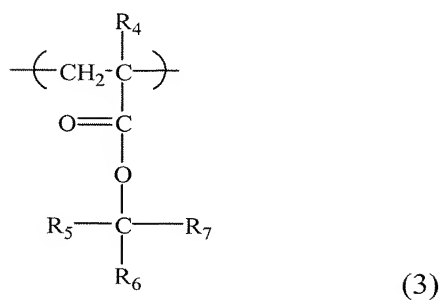
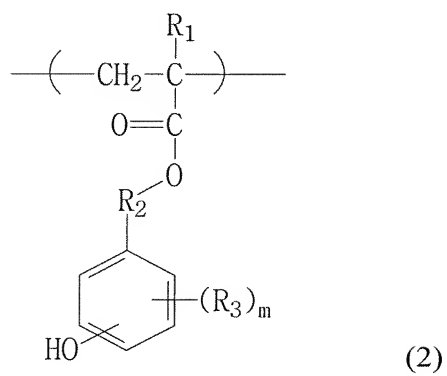
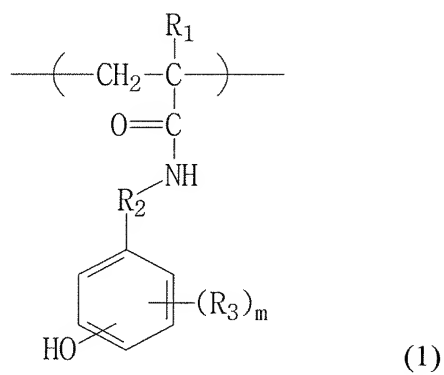
12. (New) A positive radiation-sensitive resin composition comprising:

(A) a polymer consisting of

structural units (a) represented by the following formula (1) and/or the following formula (2),

an acid-dissociable functional group (b) represented by the following formula (3), and

at least one monomer (II) selected from the group consisting of aromatic vinyl compounds, N-vinylpyrrolidone, N-vinylcaprolactam, cyano group-containing vinyl compounds, conjugated diolefins, amide group-containing vinyl compounds, carboxyl group-containing vinyl compounds, methyl acrylate, ethyl acrylate, n-propyl acrylate, n-butyl acrylate, 2-hydroxyethyl acrylate, 2-hydroxypropyl acrylate, polyethylene glycol monoacrylate, polypropylene glycol monoacrylate, glycerol monoacrylate, phenyl acrylate, benzyl acrylate, cyclohexyl acrylate, isobornyl acrylate, tricyclodecanyl acrylate methyl methacrylate, ethyl methacrylate, n-propyl methacrylate, n-butyl methacrylate, 2-hydroxyethyl methacrylate, 2-hydroxypropyl methacrylate, polyethylene glycol monomethacrylate, polypropylene glycol monomethacrylate, glycerol monomethacrylate, phenyl methacrylate, benzyl methacrylate, cyclohexyl methacrylate, isobornyl methacrylate and tricyclodecanyl methacrylate,



wherein

R₁ is a hydrogen atom or a methyl group,

R₂ is $\text{---}(\text{CH}_2)_n\text{---}$,

n is an integer of 0 to 3, R₃ is an alkyl group of 1 to 4 carbon atoms,

m is an integer of 0 to 4,

R₄ is a hydrogen atom or a methyl group,

R₅ to R₇ are each an alkyl group of 1 to 4 carbon atoms, an alicyclic hydrocarbon group of 4 to 20 carbon atoms, an aromatic group or a substituted hydrocarbon group wherein at least one hydrogen atom in any one of these hydrocarbon groups is replaced with a polar group other than a hydrocarbon group, wherein R₅ to R₇ may be the same or different, and when any two of R₅ to R₇ are alkyl groups or substituted alkyl groups, their alkyl chains may be bonded to each other to form an alicyclic hydrocarbon group of 4 to 20 carbon atoms or a substituted alicyclic hydrocarbon group;

(B) a component which generates an acid by irradiation with radiation; and

(C) an organic solvent.

13. (New) The positive radiation-sensitive resin composition as claimed in claim 12, which is a composition for producing a plated shaped article.

14. (New) The positive radiation-sensitive resin composition as claimed in claim 13, wherein the plated shaped article is a bump.

15. (New) The positive radiation-sensitive resin composition as claimed in claim 12, wherein (B) is contained in an amount of 0.1 to 20 parts by weight based on 100 parts by weight of (A), and (C) is contained in an amount of 20 to 80 parts by weight based on the total weight 100 parts by weight of the positive radiation-sensitive resin composition.

16. (New) The positive radiation-sensitive resin composition as claimed in claim 12, which further comprises an alkali-soluble resin other than the polymer (A).

17. (New) The positive radiation-sensitive resin composition as claimed in claim 12, which further comprises an acid diffusion controller.

18. (New) The positive radiation-sensitive resin composition as claimed in claim 12, wherein the component (B) is at least one compound selected from the group consisting of 4-t-butylphenyl-diphenylsulfonium trifluoromethanesulfonate, 4-t-butylphenyl-diphenylsulfonium perfluoro-n-octanesulfonate, 4-t-butylphenyl-diphenylsulfonium pyrenesulfonate and 4,7-di-n-butoxynaphthyltetrahydrothiophenium trifluoromethanesulfonate.

19. (New) A transfer film having a resin film composed of the positive radiation-sensitive resin composition of claim 12 on a support film.

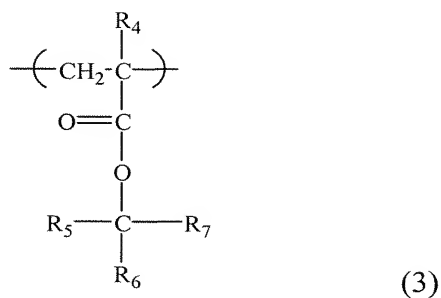
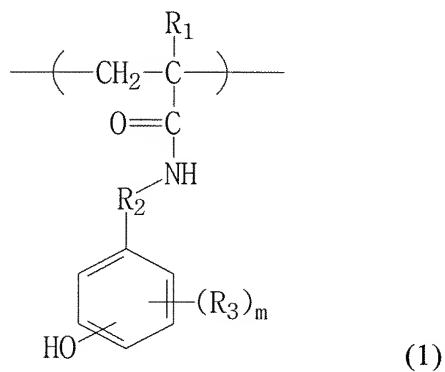
20. (New) The transfer film as claimed in claim 19, wherein the resin film has a film thickness of 20 to 100 μm .

21. (New) A process for producing a plated shaped article, comprising:

- (1) forming a resin film composed of the positive radiation-sensitive resin composition of claim 12 on a wafer having a barrier metal layer,
 - (2) exposing the resin film and then developing the resin film to form a pattern,
 - (3) depositing an electrode material by electroplating using the pattern as a mold,
- and
- (4) stripping the remaining resin film and then removing the barrier metal by etching.

22. (New) A positive radiation-sensitive resin composition comprising:

(A) a polymer containing structural units (a) represented by the following formula (1) and an acid-dissociable functional group (b) represented by the following formula (3), wherein the ratio of (b) is 5 to 95 parts by weight based on the total units of the polymer (A),



wherein

R₁ is a hydrogen atom or a methyl group,

R₂ is $\text{---}(\text{CH}_2)_n\text{---}$,

n is an integer of 0 to 3,

R₃ is an alkyl group of 1 to 4 carbon atoms, m is an integer of 0 to 4,

R₄ is a hydrogen atom or a methyl group,

R_5 to R_7 are each an alkyl group of 1 to 4 carbon atoms, an alicyclic hydrocarbon group of 4 to 20 carbon atoms, an aromatic group or a substituted hydrocarbon group wherein at least one hydrogen atom in any one of these hydrocarbon groups is replaced with a polar group other than a hydrocarbon group, wherein R_5 to R_7 may be the same or different, and when any two of R_5 to R_7 are alkyl groups or substituted alkyl groups, their alkyl chains may be bonded to each other to form an alicyclic hydrocarbon group of 4 to 20 carbon atoms or a substituted alicyclic hydrocarbon group;

- (B) a component which generates an acid by irradiation with radiation, and
- (C) an organic solvent.